




Features

- Compliant with AEC-Q200 Rev-C Stress Test Qualification for Passive Components in Automotive Applications
- Compact design to save board space - 1206 footprint
- Small size results in very fast time to react to fault events
- Symmetrical design
- Low profile
- RoHS compliant* and halogen free**
- Agency recognition: 

MF-NSMF Series - PTC Resettable Fuses

Electrical Characteristic

Model	V max. Volts	I max. Amps	I _{hold}	I _{trip}	Resistance		Max. Time To Trip		Tripped Power Dissipation
			Amperes at 23 °C		Ohms at 23 °C		Amperes at 23 °C	Seconds at 23 °C	Watts at 23 °C
			Hold	Trip	R _{Min.}	R _{1Max.}			Typ.
MF-NSMF012	30.0	10	0.12	0.29	1.35	8.50	1.0	0.20	0.4
MF-NSMF016	30.0	10	0.16	0.75	0.70	6.00	1.0	0.30	0.6
MF-NSMF020	24.0	10	0.20	0.46	0.60	2.60	1.0	0.60	0.6
MF-NSMF020X	30.0	60	0.20	0.40	0.60	3.30	1.0	0.60	0.6
MF-NSMF025X	16.0	20	0.25	0.50	0.45	2.30	8.0	0.08	0.6
MF-NSMF035	6.0	100	0.35	0.75	0.30	1.20	8.0	0.10	0.6
MF-NSMF035X	16.0	20	0.35	0.75	0.30	1.40	3.5	0.14	0.6
MF-NSMF050	13.2	100	0.50	1.00	0.15	0.70	8.0	0.10	0.4
MF-NSMF075	6.0	100	0.75	1.50	0.10	0.40	8.0	0.10	0.4
MF-NSMF110	6.0	100	1.10	2.20	0.06	0.20	8.0	0.10	0.6
MF-NSMF150	6.0	100	1.50	3.00	0.03	0.13	8.0	0.30	0.6
MF-NSMF200	6.0	100	2.00	4.00	0.02	0.085	8.0	1.00	0.7

Environmental Characteristics

Operating Temperature.....	-40 °C to +85 °C
Passive Aging.....	+85 °C, 1000 hours..... ±5 % typical resistance change
Humidity Aging.....	+85 °C, 85 % R.H. 1000 hours ±5 % typical resistance change
Thermal Shock.....	+85 °C to -40 °C, 20 times..... ±10 % typical resistance change
Solvent Resistance.....	MIL-STD-202, Method 215 No change
Vibration.....	MIL-STD-883C, Method 2007.1,..... No change Condition A
Moisture Sensitivity Level.....	1
ESD Classification (HBM).....	6

Test Procedures And Requirements For Model MF-NSMF Series

Test	Test Conditions	Accept/Reject Criteria
Visual/Mech.	Verify dimensions and materials	Per MF physical description
Resistance.....	In still air @ 23 °C.....	$R_{min} \leq R \leq R_{1max}$
Time to Trip.....	At specified current, V _{max} , 23 °C.....	$T \leq \text{max. time to trip (seconds)}$
Hold Current.....	30 min. at I _{hold}	No trip
Trip Cycle Life.....	V _{max} , I _{max} , 100 cycles.....	No arcing or burning
Trip Endurance.....	V _{max} , 48 hours.....	No arcing or burning
Solderability.....	ANSI/J-STD-002.....	95 % min. coverage
UL File Number.....	E174545 http://www.ul.com/ Follow link to Online Certificates Directory, then enter UL File No. E174545, or click here	
TÜV Certificate Number.....	R 02057213 http://www.tuvdotcom.com/ Follow link to "other certificates", enter File No. 2057213 or click here	

* RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

**Bourns considers a product to be "halogen free" if (a) the Bromine (Br) content is 900 ppm or less; (b) the Chlorine (Cl) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (Cl) content is 1500 ppm or less.

Specifications are subject to change without notice.

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Applications

- USB port protection - USB 2.0, 3.0 & OTG
- HDMI 1.4 Source protection
- PC motherboards - Plug and Play protection
- Mobile phones - Battery and port protection
- PDAs / digital cameras
- Game console port protection
- Automotive electronic control modules

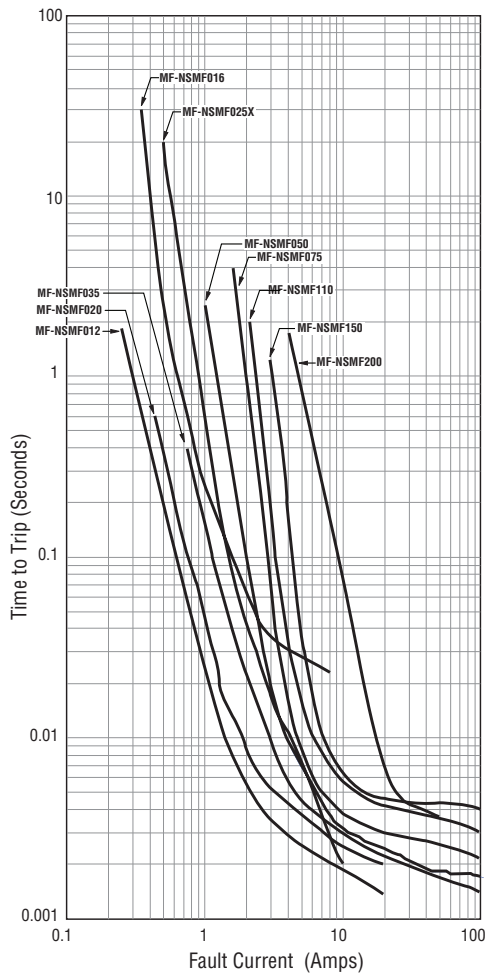
MF-NSMF Series - PTC Resettable Fuses

BOURNS®

Thermal Derating Chart - I_{hold} (Amps)

Model	Ambient Operating Temperature								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
MF-NSMF012	0.19	0.17	0.15	0.12	0.11	0.10	0.09	0.08	0.07
MF-NSMF016	0.21	0.20	0.18	0.16	0.14	0.13	0.12	0.11	0.09
MF-NSMF020	0.30	0.27	0.24	0.20	0.18	0.16	0.14	0.12	0.11
MF-NSMF020X	0.30	0.27	0.24	0.20	0.18	0.16	0.14	0.12	0.10
MF-NSMF025X	0.37	0.33	0.29	0.25	0.22	0.20	0.17	0.15	0.12
MF-NSMF035	0.51	0.46	0.40	0.35	0.30	0.27	0.24	0.22	0.18
MF-NSMF035X	0.58	0.51	0.44	0.35	0.31	0.28	0.24	0.21	0.16
MF-NSMF050	0.76	0.68	0.59	0.50	0.44	0.40	0.35	0.32	0.26
MF-NSMF075	1.11	1.00	0.85	0.75	0.67	0.61	0.52	0.50	0.42
MF-NSMF110	1.64	1.46	1.30	1.10	0.92	0.83	0.80	0.65	0.52
MF-NSMF150	2.20	1.99	1.77	1.50	1.34	1.23	1.10	1.01	0.84
MF-NSMF200	2.88	2.61	2.28	2.00	1.80	1.66	1.51	1.39	1.19

Typical Time to Trip at 23 °C



The Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.

How to Order

MF - NSMF 020 X - 2

Multifuse® Product Designator _____

Series _____
 NSMF = 1206 Surface Mount Component

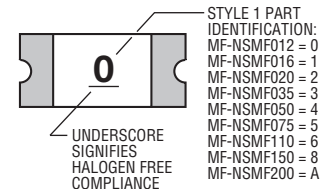
Hold Current, I_{hold} _____
 012-200 (0.12 Amps - 2.00 Amps)

Options _____
 _____ = Standard
 X = Multifuse® freeExpansion Design™

Packaging _____
 Packaged per EIA 481-1
 -2 = Tape and Reel

Typical Part Marking

Represents total content. Layout may vary.



BIWEEKLY DATE CODE WILL APPEAR ON THE PACKAGING LABEL:
 WEEK 1 AND 2 = A
 WEEK 51 AND 52 = Z

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MF-NSMF Series - PTC Resettable Fuses

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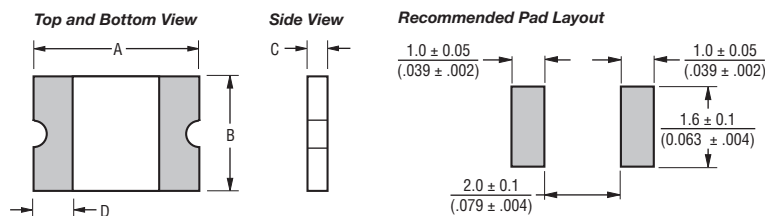
Product Dimensions

Model	A		B		C		D	Style
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	
MF-NSMF012	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.70}{(0.028)}$	$\frac{1.10}{(0.043)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF016	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.48}{(0.019)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF020	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.48}{(0.019)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF020X	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.40}{(0.016)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	2
MF-NSMF025X	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.48}{(0.019)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	2
MF-NSMF035	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.48}{(0.019)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF035X	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.40}{(0.016)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	2
MF-NSMF050	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.48}{(0.019)}$	$\frac{0.85}{(0.033)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF075	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.40}{(0.016)}$	$\frac{0.70}{(0.028)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF110	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.40}{(0.016)}$	$\frac{0.70}{(0.028)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF150	$\frac{3.00}{(0.118)}$	$\frac{3.40}{(0.134)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.40}{(0.016)}$	$\frac{0.70}{(0.028)}$	$\frac{0.25}{(0.010)}$	1
MF-NSMF200	$\frac{3.00}{(0.118)}$	$\frac{3.50}{(0.138)}$	$\frac{1.40}{(0.055)}$	$\frac{1.80}{(0.071)}$	$\frac{0.70}{(0.028)}$	$\frac{1.60}{(0.063)}$	$\frac{0.25}{(0.010)}$	1

Packaging: 3000 pcs. per reel.

DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

Style 1



Terminal material:

Electroless Ni under immersion Au

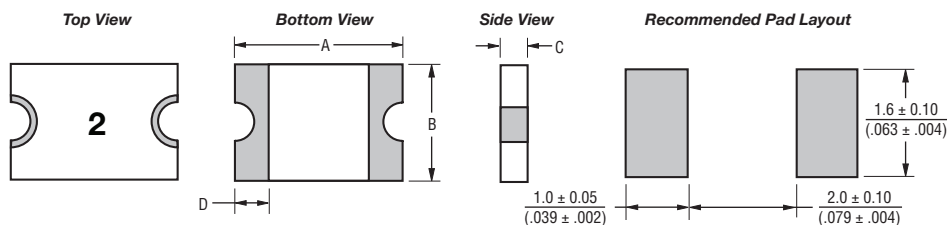
Termination pad solderability:

Standard Au finish;
Meets ANSI/J-STD-002 Category 2.

Recommended Storage:

40 °C max./70 % RH max.

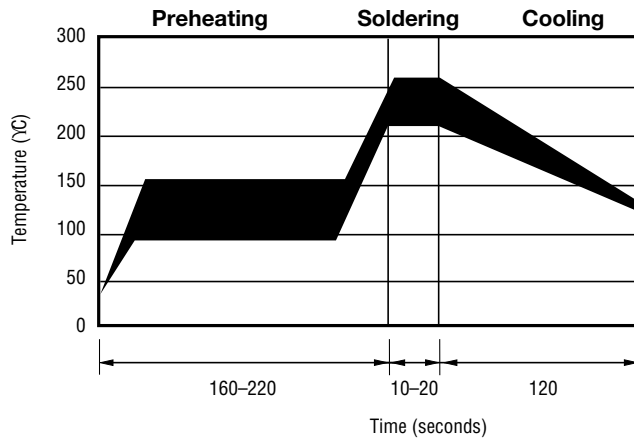
Style 2



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Solder Reflow Recommendations



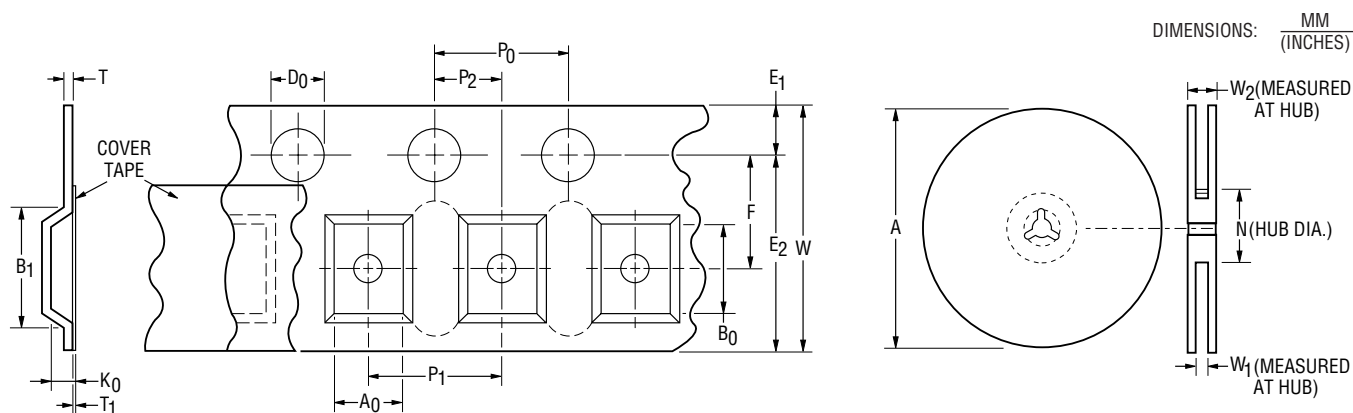
Notes:

- MF-NSMF models cannot be wave soldered. Please contact Bourns for hand soldering recommendations.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Compatible with Pb and Pb-free solder reflow profiles.
- Excess solder may cause a short circuit, especially during hand soldering. Please refer to the Multifuse® Polymer PTC Soldering Recommendation guidelines.

MF-NSMF Series Tape and Reel Specifications

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Tape Dimensions	MF-NSMF012 & MF-NSMF200 per EIA 481-1	MF-NSMF016 ~ MF-NSMF050 per EIA 481-1	MF-NSMF075 ~ MF-NSMF150 per EIA 481-1	MF-NSMF020X, MF-NSMF025X & MF-NSMF035X per EIA 481-1
W	8.0 ± 0.30 (0.315 ± 0.012)	8.0 ± 0.30 (0.315 ± 0.012)	8.0 ± 0.30 (0.315 ± 0.012)	8.0 ± 0.30 (0.315 ± 0.012)
P ₀	4.0 ± 0.10 (0.157 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)
P ₁	4.0 ± 0.10 (0.157 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)	4.0 ± 0.10 (0.157 ± 0.004)
P ₂	2.0 ± 0.05 (0.079 ± 0.002)	2.0 ± 0.05 (0.079 ± 0.002)	2.0 ± 0.05 (0.079 ± 0.002)	2.0 ± 0.05 (0.079 ± 0.002)
A ₀	1.90 ± 0.10 (0.075 ± 0.004)	1.90 ± 0.10 (0.075 ± 0.004)	1.90 ± 0.10 (0.075 ± 0.004)	1.90 ± 0.10 (0.075 ± 0.004)
B ₀	3.50 ± 0.10 (0.138 ± 0.004)	3.45 ± 0.10 (0.136 ± 0.004)	3.45 ± 0.10 (0.136 ± 0.004)	3.55 ± 0.10 (0.140 ± 0.004)
B ₁ max.	4.35 (0.171)	4.35 (0.171)	4.35 (0.171)	4.35 (0.171)
D ₀	$1.5 + 0.10/-0.0$ (0.059 + 0.004/-0)	$1.5 + 0.10/-0.0$ (0.059 + 0.004/-0)	$1.5 + 0.10/-0.0$ (0.059 + 0.004/-0)	$1.5 + 0.10/-0.0$ (0.059 + 0.004/-0)
F	3.5 ± 0.05 (0.138 ± 0.002)	3.5 ± 0.05 (0.138 ± 0.002)	3.5 ± 0.05 (0.138 ± 0.002)	3.5 ± 0.05 (0.138 ± 0.002)
E ₁	1.75 ± 0.10 (0.069 ± 0.004)	1.75 ± 0.10 (0.069 ± 0.004)	1.75 ± 0.10 (0.069 ± 0.004)	1.75 ± 0.10 (0.069 ± 0.004)
E ₂ min.	6.25 (0.246)	6.25 (0.246)	6.25 (0.246)	6.25 (0.246)
T max.	0.6 (0.024)	0.6 (0.024)	0.6 (0.024)	0.6 (0.024)
T ₁ max.	0.1 (0.004)	0.1 (0.004)	0.1 (0.004)	0.1 (0.004)
K ₀	1.35 ± 0.10 (0.053 ± 0.004)	1.04 ± 0.10 (0.041 ± 0.004)	0.85 ± 0.10 (0.033 ± 0.004)	0.80 ± 0.10 (0.032 ± 0.004)
Leader min.	390 (15.35)	390 (15.35)	390 (15.35)	390 (15.35)
Trailer min.	160 (6.30)	160 (6.30)	160 (6.30)	160 (6.30)
Reel Dimensions				
A max.	185 (7.28)	185 (7.28)	185 (7.28)	185 (7.28)
N min.	50 (1.97)	50 (1.97)	50 (1.97)	50 (1.97)
W ₁	$8.4 + 1.5/-0.0$ (0.331 + 0.059/-0.0)	$8.4 + 1.5/-0.0$ (0.331 + 0.059/-0.0)	$8.4 + 1.5/-0.0$ (0.331 + 0.059/-0.0)	$8.4 + 1.5/-0.0$ (0.331 + 0.059/-0.0)
W ₂ max.	14.4 (0.567)	14.4 (0.567)	14.4 (0.567)	14.4 (0.567)



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Features

- RoHS compliant*
- Protects one line or one I/O port
- Bidirectional configuration
- ESD protection 30 kV max.
- Low capacitance: ~3 pF typical
- Replaces 0805 MLV devices

Applications

- Cellular phones
- PDAs and notebooks
- Digital cameras
- MP3 players and GPS
- USB interface

CDSOD323-TxxC - TVS Diode Array Series

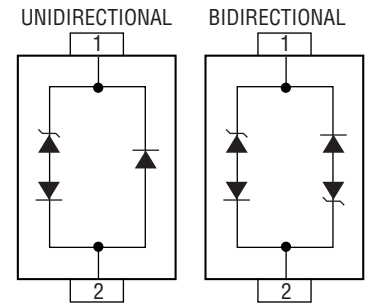
General Information

Portable communications, computing and video equipment manufacturers are challenging the semiconductor industry to develop increasingly smaller electronic components.

Bourns offers Transient Voltage Suppressor Array diodes for surge and ESD protection applications, in SOD323 package size format. The Transient Voltage Suppressor Array series offers a choice of voltage types ranging from 3 V to 24 V in a unidirectional or bidirectional configuration. Bourns® Chip Diodes conform to JEDEC standards, are easy to handle on standard pick and place equipment and their flat configuration minimizes roll away.

The Bourns® device will assist compliance with IEC 61000-4-2 (ESD), IEC 61000-4-4 (EFT) and IEC 61000-4-5 (Surge) requirements.

Note: For 12 V and 24 V VDSL applications, the CDSOD323-TxxC-DSL family of devices is recommended.



Electrical & Thermal Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power (t _p = 8/20 μs)	P _{PP}	350	W
Operating Temperature	T _J	-55 to +150	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Parameter	Symbol	CDSOD323-								Unit
		Uni-T03	Bi-T03C	Uni-T05	Bi-T05C	Uni-T08	Bi-T08C	Uni-T12	Bi-T12C	
Minimum Breakdown Voltage @ 1 mA	V _{BR}	4.0		6.0		8.5		13.3		V
Working Peak Voltage	V _{WM}	3.3		5.0		8.0		12.0		V
Maximum Clamping Voltage @ I _P = 1 A	V _C	7.0		9.8		13.4		19.0		V
Typical Clamping Voltage @ 8/20 μs @ I _{PP}	V _C	19.0 V @ 20 A		18.3 V @ 17 A		18.5 V @ 17 A		28.3 V @ 11 A		V
Maximum Leakage Current @ V _{WM}	I _D	5		5		2		1		μA
Typical Capacitance @ 0 V, 1 MHz	C _J	3								pF

Parameter	Symbol	CDSOD323-						Unit
		Uni-T15	Bi-T15C	Uni-T18	Bi-T18C	Uni-T24	Bi-T24C	
Minimum Breakdown Voltage @ 1 mA	V _{BR}	16.7		20.0		26.7		V
Working Peak Voltage	V _{WM}	15.0		18.0		24.0		V
Maximum Clamping Voltage @ I _P = 1 A	V _C	24.0		29.0		43.0		V
Typical Clamping Voltage @ 8/20 μs @ I _{PP}	V _C	31.8 V @ 10 A		45.0 V @ 8 A		56.0 V @ 6 A		V
Maximum Leakage Current @ V _{WM}	I _D	1						μA
Typical Capacitance @ 0 V, 1 MHz	C _J	3						pF

Notes:

1. Part numbers with suffix "C" indicate bidirectional device, i.e. CDSOD323-T05C.
2. For bidirectional devices only, the electrical specifications apply in both directions.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

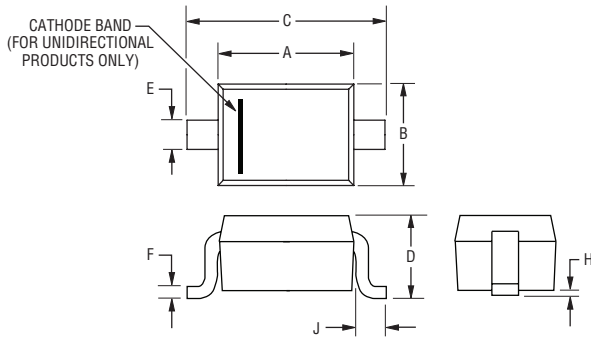
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CDSOD323-TxxC - TVS Diode Array Series



Product Dimensions

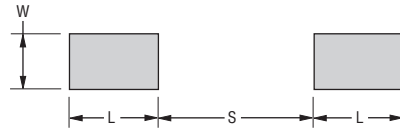
This is an RoHS compliant molded JEDEC SOD-323 package with 100 % Sn plating on the terminations. It weighs approximately 30 mg and has a flammability rating of UL 94V-0.



Dimensions	
A	$\frac{1.60 - 1.90}{(0.063 - 0.075)}$
B	$\frac{1.15 - 1.45}{(0.045 - 0.057)}$
C	$\frac{2.39 - 2.70}{(0.094 - 0.106)}$
D	$\frac{0.92 - 1.14}{(0.036 - 0.045)}$
E	$\frac{0.25 - 0.40}{(0.010 - 0.016)}$
F	$\frac{0.08 - 0.20}{(0.003 - 0.008)}$
H	$\frac{0.13}{(0.005)}$ MAX.
J	$\frac{0.30 - 0.45}{(0.012 - 0.018)}$

DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

Recommended Footprint



Dimensions (Nominal)	
L	$\frac{0.80}{(0.031)}$
S	$\frac{1.40}{(0.055)}$
W	$\frac{0.50}{(0.020)}$

DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

Typical Part Marking

Each device has device marking outlined below and the unidirectional devices have an additional Polarity Band indicating the cathode.

CDSOD323-T033
CDSOD323-T03C3C
CDSOD323-T055
CDSOD323-T05C5C
CDSOD323-T088
CDSOD323-T08C8C
CDSOD323-T122
CDSOD323-T12C2C
CDSOD323-T156
CDSOD323-T15C6C
CDSOD323-T181
CDSOD323-T18C1C
CDSOD323-T244
CDSOD323-T24C4C

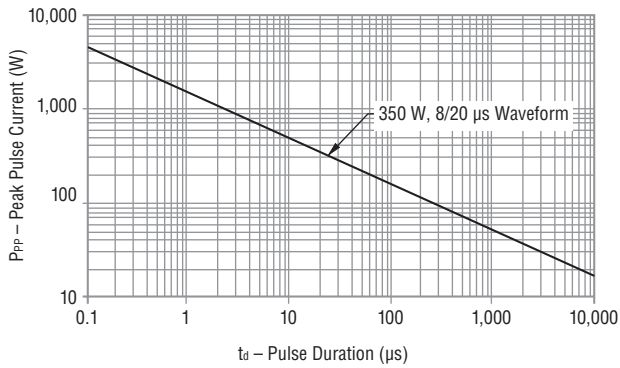
Environmental Specifications

Moisture Sensitivity Level1
ESD Classification (HBM)3B

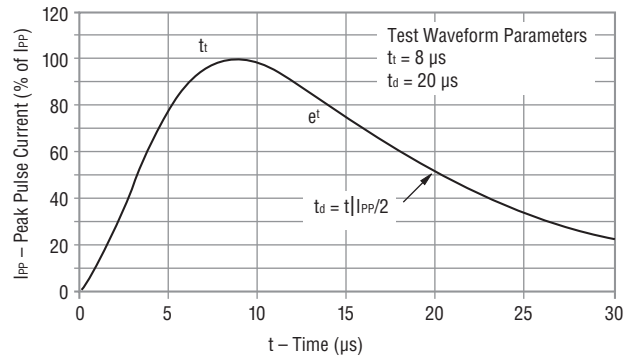
CDSOD323-TxxC - TVS Diode Array Series

Performance Graphs

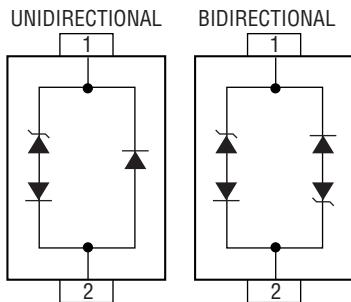
Peak Pulse Power vs Pulse Time



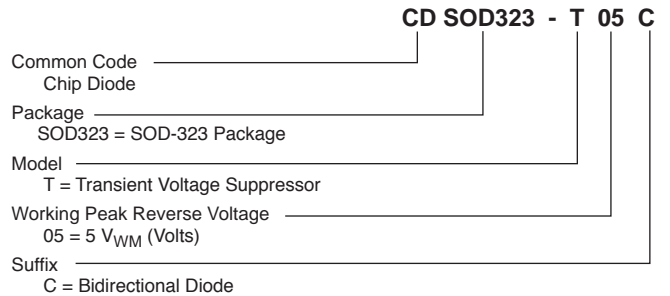
Pulse Waveform



Block Diagram



How to Order



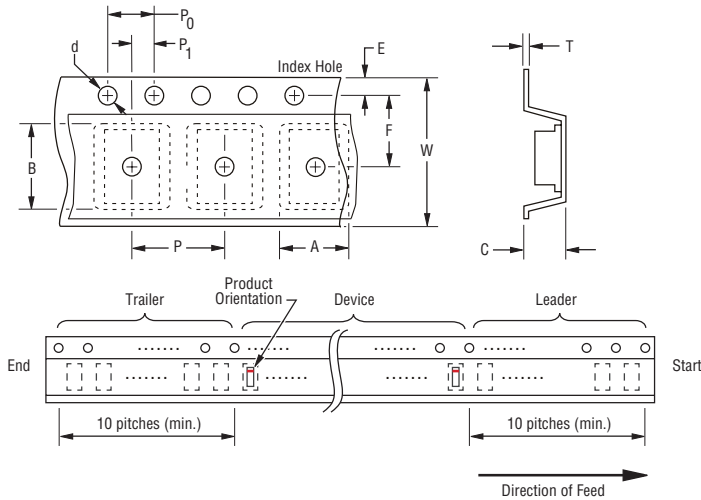
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CDSOD323-TxxC - TVS Diode Array Series

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Packaging Information

The product is packaged in tape and reel format per EIA-481 standard.



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

Item	Symbol	SOD-323
Carrier Width	A	$\frac{1.55 \pm 0.10}{(0.061 \pm 0.004)}$
Carrier Length	B	$\frac{2.90 \pm 0.10}{(0.114 \pm 0.004)}$
Carrier Depth	C	$\frac{1.35 \pm 0.10}{(0.053 \pm 0.004)}$
Sprocket Hole	d	$\frac{1.55 \pm 0.05}{(0.061 \pm 0.002)}$
Reel Outside Diameter	D	$\frac{178}{(7.008)}$
Reel Inner Diameter	D ₁	$\frac{80.0}{(3.150)}$ MIN.
Feed Hole Diameter	D ₂	$\frac{13.0 \pm 0.20}{(0.512 \pm 0.008)}$
Sprocket Hole Position	E	$\frac{1.75 \pm 0.10}{(0.069 \pm 0.004)}$
Punch Hole Position	F	$\frac{3.50 \pm 0.05}{(0.138 \pm 0.002)}$
Punch Hole Pitch	P	$\frac{4.00 \pm 0.10}{(0.157 \pm 0.004)}$
Sprocket Hole Pitch	P ₀	$\frac{4.00 \pm 0.10}{(0.157 \pm 0.004)}$
Embossment Center	P ₁	$\frac{2.00 \pm 0.05}{(0.079 \pm 0.002)}$
Overall Tape Thickness	T	$\frac{0.20 \pm 0.10}{(0.008 \pm 0.004)}$
Tape Width	W	$\frac{8.00 \pm 0.20}{(0.315 \pm 0.008)}$
Reel Width	W ₁	$\frac{13.5}{(0.531)}$ MAX.
Quantity per Reel	--	3000

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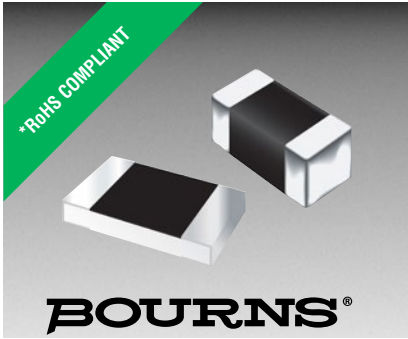
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REV. 01/18

Specifications are subject to change without notice. The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.



Features

- RoHS compliant*
- ESD protection >25 kV
- Low capacitance <0.5 pF
- Low leakage current <50 nA

Applications

- HDMI 1.4
- Digital Visual Interface (DVI)
- USB 3.0 / USB OTG
- Memory protection
- SIM card ports

ChipGuard® MLC Series - ESD Protectors

General Information

The ChipGuard® MLC Series has been specifically designed to protect sensitive electronic components from electrostatic discharge damage. The MLC family has been designed to protect equipment to IEC61000-4-2, Level 4 (±8 kV Contact / ±15 kV Air Discharge) ESD specifications targeted for high speed USB 3.0/USB OTG, HDMI 1.4, DVI or IEEE1394 applications.

The ChipGuard® MLC Series has been manufactured to provide low 0.5 pF capacitance and leakage currents less than 5 nA with excellent clamp qualities, making the family almost transparent under normal working conditions.

Device Symbol



Electrical Characteristics @ 25 °C (unless otherwise noted)

Parameter	Symbol	CG0402MLC-								Unit
		3.3LG	05LG	12LG	24LG	3.3LGA	05LGA	12LGA	24LGA	
Typical Continuous Operating Voltage	V _{DC}	3.3	5	12	24	3.3	5	12	24	V
Typical Clamping Voltage (Note 1)	V _C	25								V
Maximum Capacitance @ 1 VRMS 1 MHz	C _O	0.5								pF
Maximum Leakage Current @ Max. VDC	I _L	5								nA
Typical Trigger Voltage (Note 2)	V _T	250								V
Maximum Response Time	R _T	1								ns
ESD Protection: Per IEC 61000-4-2 Level 4 Min. Contact Discharge Min. Air Discharge Min. Air Discharge		±8 ±15 (Note 3) ±25								kV kV kV
Operating Temperature	T _{OPR}	-40 to +85				-40 to +125				°C
Storage Temperature	T _{STG}	-55 to +150								°C

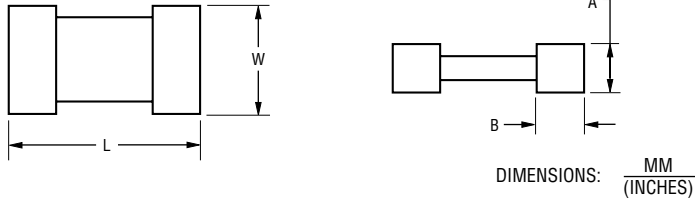
Parameter	Symbol	CG0603MLC-								Unit
		3.3LE	05LE	12LE	24LE	3.3LEA	05LEA	12LEA	24LEA	
Typical Continuous Operating Voltage	V _{DC}	3.3	5	12	24	3.3	5	12	24	V
Typical Clamping Voltage (Note 1)	V _C	25	25	25						V
Maximum Capacitance @ 1 VRMS 1 MHz	C _O	0.5								pF
Maximum Leakage Current @ Max. VDC	I _L	5	5	5						nA
Typical Trigger Voltage (Note 2)	V _T	250	250	250						V
Maximum Response Time	R _T	1								ns
ESD Protection: Per IEC 61000-4-2 Level 4 Min. Contact Discharge Min. Air Discharge Min. Air Discharge		±8 ±15 (Note 3) ±25								kV kV kV
Operating Temperature	T _{OPR}	-40 to +85				-40 to +125				°C
Storage Temperature	T _{STG}	-55 to +150								°C

- Notes: 1. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement 30 ns after initiation of pulse.
 2. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement at maximum pulse voltage.
 3. IEC 61000-4-2 ESD Performance will meet minimum 1000 reps without degradation in performance.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.
 Specifications are subject to change without notice.

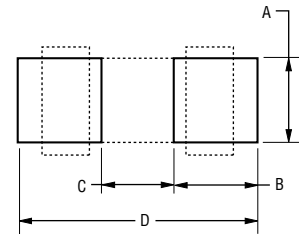
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
 Users should verify actual device performance in their specific applications.

Product Dimensions



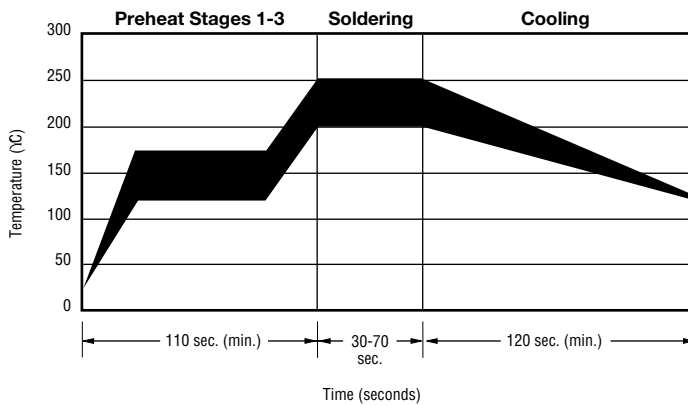
Dimension	CG0402 Series	CG0603 Series
L	$\frac{1.00 \pm 0.15}{(0.04 \pm 0.006)}$	$\frac{1.60 \pm 0.20}{(0.064 \pm 0.008)}$
W	$\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$	$\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$
A	$\frac{0.36 \pm 0.05}{(0.014 \pm 0.002)}$	$\frac{0.45 \pm 0.10}{(0.018 \pm 0.004)}$
B	$\frac{0.25 \pm 0.15}{(0.10 \pm 0.006)}$	$\frac{0.30 \pm 0.20}{(0.012 \pm 0.008)}$

Recommended Pad Layout



Dim.	CG0402 Series	CG0603 Series
A	$\frac{0.51}{(0.020)}$	$\frac{0.76}{(0.030)}$
B	$\frac{0.61}{(0.024)}$	$\frac{1.02}{(0.040)}$
C	$\frac{0.51}{(0.020)}$	$\frac{0.50}{(0.020)}$
D	$\frac{1.70}{(0.067)}$	$\frac{2.54}{(0.100)}$

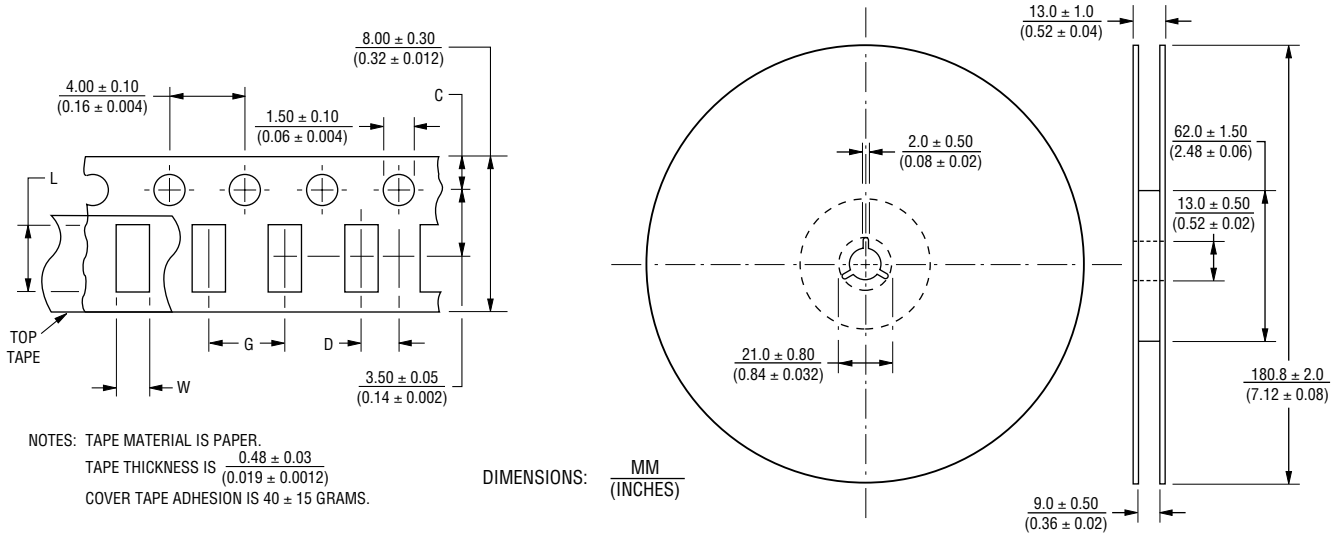
Solder Reflow Recommendations



A	Stage 1 Preheat	Ambient to Preheating Temperature	30 s to 60 s
B	Stage 2 Preheat	140 °C to 160 °C	60 s to 120 s
C	Stage 3 Preheat	Preheat to 200 °C	20 s to 40 s
D	Main Heating	200 °C 210 °C 220 °C 230 °C 240 °C 250 °C to 255 °C	60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s 5 s
E	Cooling	200 °C to 100 °C	1 °C/s to 4 °C/s

- This product can be damaged by rapid heating, cooling or localized heating.
- Heat shocks should be avoided. Preheating and gradual cooling recommended.
- Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.
- Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds. A solder gun under 30 watts is recommended.

Packaging Dimensions



Dimension	CG0402 Series	CG0603 Series
C	$\frac{1.75 \pm 0.05}{(0.04 \pm 0.002)}$	$\frac{1.75 \pm 0.10}{(0.04 \pm 0.004)}$
D	$\frac{2.00 \pm 0.02}{(0.08 \pm 0.0008)}$	$\frac{2.00 \pm 0.05}{(0.08 \pm 0.002)}$
L	$\frac{1.12 \pm 0.03}{(0.045 \pm 0.0012)}$	$\frac{1.80 \pm 0.20}{(0.072 \pm 0.008)}$
W	$\frac{0.62 \pm 0.03}{(0.025 \pm 0.0012)}$	$\frac{0.90 \pm 0.20}{(0.036 \pm 0.008)}$
G	$\frac{2.0 \pm 0.05}{(0.08 \pm 0.002)}$	$\frac{4.0 \pm 0.05}{(0.16 \pm 0.002)}$

How to Order

CG 0n0n MLC - n.n x x x

ChipGuard®
 Product Designator
 Package Option
 0402 = 0402 Package
 0603 = 0603 Package
 Multilayer Series Designator
 Operating Voltage**
 3.3 = 3.3 V
 05 = 5 V
 12 = 12 V
 24 = 24 V
 Low Leakage Current Option
 L = Low Leakage Current
 Blank = Standard Product
 Tape & Reel Packaging
 E = 5,000 pcs. per reel (0603 Package)
 G = 10,000 pcs. per reel (0402 Package)
 Operating Temperature Option
 A = Higher +125 °C Operating Temperature
 Blank = Standard Product
 ** Only models lower than 10 volts require decimal point.

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